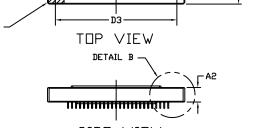
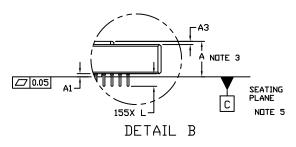
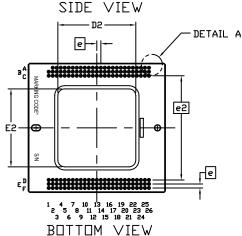
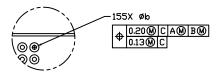


DATE 24 JAN 2017









DETAIL A

	MILLIMETERS			
DIM	MIN.	N□M.	MAX.	
Α	5.62 REF			
A1	0.45	0.50	0.55	
A2	4.15	4.61	5.07	
A3	0.50 REF			
b	0.25	0.30	0.35	
D	43.10	43.50	43.90	
D1	28.42	28.50	28.58	
D2	24.55	24.70	24.85	
D3	38.15	38.50	38.85	
E	40.59	41.00	41.41	
E1	28.42	28.50	28.58	
E2	24.55	24.70	24.85	
е	1.27 BSC			
e2	33.02 B2C			
F	1.65	1.75	1.85	
F1	1.65	1.75	1.85	
F2	2.57	2.72	2.87	
L	1.80	2.00	2.20	

NOTES:

NOTE 6

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
- 4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
- THE SEATING PLANE IS DEFINED BY THE DUTER HEATSINK SURFACE.
- 6. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.

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DESCRIPTION:	CPGA155 43.5X41	•	PAGE 1 OF 1	

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